

**In the Specification:**

Please delete the following paragraph(s)/section(s)/abstract and replace such paragraph(s)/section(s)/abstract pursuant to 37 CFR 1.121(b)(1)(ii) with the "clean" version set forth below. Entry is respectfully requested. A version with markings to show the changes made pursuant to 37 CFR 1.121(b)(1)(iii) is attached hereto as Appendix A.

✓ **Paragraph at page 1, line 5 to page 1, line 9:**

β<sup>1</sup> The present invention relates to a mounting structure for a printed circuit board.

✓ **Paragraph at page 1, line 22 to page 2, line 7:**

β<sup>2</sup> However, in order to enhance wettability of the semiconductor package with the solder 5, a plating 6 is provided over the pad 2 and the head portion 3a of the connection wiring 3. Also, for mutual insulation between adjacent pad 2 and the connection wiring 3, a solder resist 7 is applied on the surface layer of the printed circuit board 1. As shown in Figs. 4 and 5, the solder resist 7 contacts with the plating 6 at the outer circumference of the pad 2 and the connection wiring 3 is covered by the solder resist 7. The reference numeral 10 denotes a runout for the solder resist provided between the pad 2 and the solder resist 7.

✓ **Paragraph at page 3, line 1 to page 3, line 4:**

β<sup>3</sup> Due to this stress F, breakage of copper wire 3 is caused at the boundary portion of the nickel plating 6 and the solder resist 7. By breakage of the copper wiring 3, the semiconductor device can be broken.